

ABSTRACT

A nonconducting substrate forming a strip or a panel on which a plurality of carrier elements having respective boundary lines are formed. The substrate includes a contact side, an insertion side opposite the contact side, and a conducting insertion-side metallization provided on the insertion side. The insertion-side metallization is formed such that an electrical connection can take place by flip-chip bonding between contact points of an integrated circuit to be applied to the insertion side and the insertion-side metallization.